

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHENG-PIN GAO	08/07/2015
YONG-CHUN XU	08/07/2015
CHIH-CHING HSU	08/07/2015
HAO HAN	08/07/2015
RECEIVING PARTY DATA	
Name:	FOXCONN INTERCONNECT TECHNOLOGY LIMITED
Street Address:	Floor 4, Willow House, Cricket Square, P O Box 2804
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14831889
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NAME OF SUBMITTER:	WEI TE CHUNG
SIGNATURE:	/WEI TE CHUNG/
DATE SIGNED:	08/21/2015
Total Attachments: 2	
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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. SHENG-PIN GAO , residing at Kunshan, China
- 2. YONG-CHUN XU , residing at Kunshan, China
- 3. CHIH-CHING HSU , residing at New Taipei, Taiwan
- 4. HAO HAN , residing at Kunshan, China
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: FOXCONN INTERCONNECT TECHNOLOGY LIMITED having a principal place of business at Floor 4, Willow House, Cricket Square, P O Box 2804, Grand Cayman KY1-1112 , Cayman Islands, hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **HIGH BANDWIDTH JACK WITH RJ45 BACKWARDS COMPATIBILITY HAVING AN IMPROVED STRUCTURE FOR REDUCING NOISE** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE' s full protection and title in and to the invention hereby transferred.

1.	<u>SHENG-PIN GAO</u> SHENG-PIN GAO	<u>08/07/2015</u> Date
2.	<u>Yong-chun Xu</u> YONG-CHUN XU	<u>08/07/2015</u> Date
3.	<u>CHIH-CHING HSU</u> CHIH-CHING HSU	<u>08/07/2015</u> Date
4.	<u>Hao Han</u> HAO HAN	<u>08/07/2015</u> Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date